Abstract
Philips Semiconductors (now NXP Semiconductors) developed a simple bidirectional 2-wire bus for efficient inter-IC control. This bus is called the Inter-IC or I2C-bus. Only two bus lines are required: a serial data line (SDA) and a serial clock line (SCL). Serial, 8-bit oriented, bidirectional data transfers can be made at up to 100 kbit/s in the Standard-mode, up to 400 kbit/s in the Fast-mode, up to 1 Mbit/s in the Fast-mode Plus (Fm+), or up to 3.4 Mbit/s in the High-speed mode.
<table>
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<tr>
<th>Rev</th>
<th>Date</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>03</td>
<td>20070619</td>
<td>Many of today's applications require longer buses and/or faster speeds. Fast-mode plus was introduced to meet this need by increasing drive strength by as much as 10x and increasing the data rate to 1 Mbit/s while maintaining downward compatibility to Fast-mode and Standard-mode speeds and software commands.</td>
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<td></td>
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<td>Modifications:</td>
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<td></td>
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<td>• Re-ordered sections and clarified several requirements</td>
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<tr>
<td></td>
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<td>• Added description of Fast-mode Plus (Fm+) specifications</td>
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<td>• Added description of the Device ID Field</td>
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<td>• Added Bus Clear procedures</td>
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<td>• Moved level shifting information to a separate application note (AN10441)</td>
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<td>• Clarified the process of sizing $R_p$</td>
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<td></td>
<td></td>
<td>• Added limits for $t_{VD;DAT}$ and $t_{VD;ACK}$</td>
</tr>
<tr>
<td>2.1</td>
<td>2000</td>
<td>Version 2.1 of the I²C-bus specification</td>
</tr>
<tr>
<td>2.0</td>
<td>1998</td>
<td>The I²C-bus has become a de facto world standard that is now implemented in over 1000 different ICs and licensed to more than 50 companies. Many of today's applications, however, require higher bus speeds and lower supply voltages. This updated version of the I²C-bus specification meets those requirements.</td>
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<tr>
<td>1.0</td>
<td>1992</td>
<td>Version 1.0 of the I²C-bus specification</td>
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<tr>
<td>Original</td>
<td>1982</td>
<td>first release</td>
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Contact information

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1. Introduction

The I²C-bus is a de facto world standard that is now implemented in over 1000 different ICs manufactured by more than 50 companies. Additionally, the versatile I²C-bus is used in a variety of control architectures such as System Management Bus (SMBus), Power Management Bus (PMBus), Intelligent Platform Management Interface (IPMI), and Advanced Telecom Computing Architecture (ATCA).

This document will assist device and system designers to understand how the I²C-bus works and implement a working application. Various operating modes are described. It contains a comprehensive introduction to the I²C-bus data transfer, handshaking and bus arbitration schemes. Detailed sections cover the timing and electrical specifications for the I²C-bus in each of its operating modes.

Designers of I²C-compatible chips should use this document as a reference and ensure that new devices meet all limits specified in this document. Designers of systems that include I²C devices should review this document and also refer to individual component data sheets.

2. I²C-bus features

In consumer electronics, telecommunications and industrial electronics, there are often many similarities between seemingly unrelated designs. For example, nearly every system includes:

• Some intelligent control, usually a single-chip microcontroller
• General-purpose circuits like LCD and LED drivers, remote I/O ports, RAM, EEPROM, real-time clocks or A/D and D/A converters
• Application-oriented circuits such as digital tuning and signal processing circuits for radio and video systems, temperature sensors, and smart cards

To exploit these similarities to the benefit of both systems designers and equipment manufacturers, as well as to maximize hardware efficiency and circuit simplicity, Philips Semiconductors (now NXP Semiconductors) developed a simple bidirectional 2-wire bus for efficient inter-IC control. This bus is called the Inter IC or I²C-bus. All I²C-bus compatible devices incorporate an on-chip interface which allows them to communicate directly with each other via the I²C-bus. This design concept solves the many interfacing problems encountered when designing digital control circuits.

Here are some of the features of the I²C-bus:

• Only two bus lines are required; a serial data line (SDA) and a serial clock line (SCL).
• Each device connected to the bus is software addressable by a unique address and simple master/slave relationships exist at all times; masters can operate as master-transmitters or as master-receivers.
• It is a true multi-master bus including collision detection and arbitration to prevent data corruption if two or more masters simultaneously initiate data transfer.
• Serial, 8-bit oriented, bidirectional data transfers can be made at up to 100 kbit/s in the Standard-mode, up to 400 kbit/s in the Fast-mode, up to 1 Mbit/s in Fast-mode Plus, or up to 3.4 Mbit/s in the High-speed mode.
• On-chip filtering rejects spikes on the bus data line to preserve data integrity.
• The number of ICs that can be connected to the same bus is limited only by a
  maximum bus capacitance. More capacitance may be allowed under some
  conditions. Refer to Section 7.2.

Figure 1 shows an example of \( \textbf{I}^2\textbf{C} \)-bus applications.

2.1 Designer benefits

\( \textbf{I}^2\textbf{C} \)-bus compatible ICs allow a system design to rapidly progress directly from a
functional block diagram to a prototype. Moreover, since they ‘clip’ directly onto the
\( \textbf{I}^2\textbf{C} \)-bus without any additional external interfacing, they allow a prototype system to be
modified or upgraded simply by ‘clipping’ or ‘unclipping’ ICs to or from the bus.

Here are some of the features of \( \textbf{I}^2\textbf{C} \)-bus compatible ICs that are particularly attractive to
designers:

• Functional blocks on the block diagram correspond with the actual ICs; designs
  proceed rapidly from block diagram to final schematic.
• No need to design bus interfaces because the \( \textbf{I}^2\textbf{C} \)-bus interface is already integrated
  on-chip.
• Integrated addressing and data-transfer protocol allow systems to be completely
  software-defined.
The same IC types can often be used in many different applications.
Design-time reduces as designers quickly become familiar with the frequently used functional blocks represented by I²C-bus compatible ICs.
ICs can be added to or removed from a system without affecting any other circuits on the bus.
Fault diagnosis and debugging are simple; malfunctions can be immediately traced.
Software development time can be reduced by assembling a library of reusable software modules.

In addition to these advantages, the CMOS ICs in the I²C-bus compatible range offer designers special features which are particularly attractive for portable equipment and battery-backed systems.

They all have:
• Extremely low current consumption
• High noise immunity
• Wide supply voltage range
• Wide operating temperature range.

2.2 Manufacturer benefits
I²C-bus compatible ICs not only assist designers, they also give a wide range of benefits to equipment manufacturers because:
• The simple 2-wire serial I²C-bus minimizes interconnections so ICs have fewer pins and there are not so many PCB tracks; result—smaller and less expensive PCBs.
• The completely integrated I²C-bus protocol eliminates the need for address decoders and other ‘glue logic’.
• The multi-master capability of the I²C-bus allows rapid testing and alignment of end-user equipment via external connections to an assembly-line.
• The availability of I²C-bus compatible ICs in a variety of leadless packages reduces space requirements even more.

These are just some of the benefits. In addition, I²C-bus compatible ICs increase system design flexibility by allowing simple construction of equipment variants and easy upgrading to keep designs up-to-date. In this way, an entire family of equipment can be developed around a basic model. Upgrades for new equipment, or enhanced-feature models (i.e., extended memory, remote control, etc.) can then be produced simply by clipping the appropriate ICs onto the bus. If a larger ROM is needed, it is simply a matter of selecting a microcontroller with a larger ROM from our comprehensive range. As new ICs supersede older ones, it is easy to add new features to equipment or to increase its performance by simply unclipping the outdated IC from the bus and clipping on its successor.
2.3 IC designer benefits

Designers of microcontrollers are frequently under pressure to conserve output pins. The I²C protocol allows connection of a wide variety of peripherals without the need for separate addressing or chip enable signals. Additionally, a microcontroller that includes an I²C interface will be more successful in the marketplace due to the wide variety of existing peripheral devices available.

3. The I²C-bus protocol

Two wires, serial data (SDA) and serial clock (SCL), carry information between the devices connected to the bus. Each device is recognized by a unique address (whether it is a microcontroller, LCD driver, memory or keyboard interface) and can operate as either a transmitter or receiver, depending on the function of the device. An LCD driver may be only a receiver, whereas a memory can both receive and transmit data. In addition to transmitters and receivers, devices can also be considered as masters or slaves when performing data transfers (see Table 1). A master is the device which initiates a data transfer on the bus and generates the clock signals to permit that transfer. At that time, any device addressed is considered a slave.

<table>
<thead>
<tr>
<th>Term</th>
<th>Description</th>
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<tbody>
<tr>
<td>Transmitter</td>
<td>the device which sends data to the bus</td>
</tr>
<tr>
<td>Receiver</td>
<td>the device which receives data from the bus</td>
</tr>
<tr>
<td>Master</td>
<td>the device which initiates a transfer, generates clock signals and terminates a transfer</td>
</tr>
<tr>
<td>Slave</td>
<td>the device addressed by a master</td>
</tr>
<tr>
<td>Multi-master</td>
<td>more than one master can attempt to control the bus at the same time without corrupting the message</td>
</tr>
<tr>
<td>Arbitration</td>
<td>procedure to ensure that, if more than one master simultaneously tries to control the bus, only one is allowed to do so and the winning message is not corrupted</td>
</tr>
<tr>
<td>Synchronization</td>
<td>procedure to synchronize the clock signals of two or more devices</td>
</tr>
</tbody>
</table>

The I²C-bus is a multi-master bus. This means that more than one device capable of controlling the bus can be connected to it. As masters are usually microcontrollers, let’s consider the case of a data transfer between two microcontrollers connected to the I²C-bus (see Figure 2).
This highlights the master-slave and receiver-transmitter relationships to be found on the I²C-bus. It should be noted that these relationships are not permanent, but only depend on the direction of data transfer at that time. The transfer of data would proceed as follows:

1. Suppose microcontroller A wants to send information to microcontroller B:
   - microcontroller A (master), addresses microcontroller B (slave)
   - microcontroller A (master-transmitter), sends data to microcontroller B (slave-receiver)
   - microcontroller A terminates the transfer.

2. If microcontroller A wants to receive information from microcontroller B:
   - microcontroller A (master) addresses microcontroller B (slave)
   - microcontroller A (master-receiver) receives data from microcontroller B (slave-transmitter)
   - microcontroller A terminates the transfer.

Even in this case, the master (microcontroller A) generates the timing and terminates the transfer.

The possibility of connecting more than one microcontroller to the I²C-bus means that more than one master could try to initiate a data transfer at the same time. To avoid the chaos that might ensue from such an event, an arbitration procedure has been developed. This procedure relies on the wired-AND connection of all I²C interfaces to the I²C-bus.

If two or more masters try to put information onto the bus, the first to produce a ‘one’ when the other produces a ‘zero’ will lose the arbitration. The clock signals during arbitration are a synchronized combination of the clocks generated by the masters using the wired-AND connection to the SCL line (for more detailed information concerning arbitration see Section 3.8).

Generation of clock signals on the I²C-bus is always the responsibility of master devices; each master generates its own clock signals when transferring data on the bus. Bus clock signals from a master can only be altered when they are stretched by a slow slave device holding down the clock line or by another master when arbitration occurs.
Table 2 summarizes the use of mandatory and optional portions of the I²C-bus specification and which system configurations use them.

### Table 2: Applicability of I²C-bus protocol features

<table>
<thead>
<tr>
<th>Feature</th>
<th>Configuration</th>
<th>Single master</th>
<th>Multi-master</th>
<th>Slave[1]</th>
</tr>
</thead>
<tbody>
<tr>
<td>START condition</td>
<td>M</td>
<td>M</td>
<td>M</td>
<td>M</td>
</tr>
<tr>
<td>STOP condition</td>
<td>M</td>
<td>M</td>
<td>M</td>
<td>M</td>
</tr>
<tr>
<td>Acknowledge</td>
<td>M</td>
<td>M</td>
<td>M</td>
<td>M</td>
</tr>
<tr>
<td>Synchronization</td>
<td>n/a</td>
<td>M</td>
<td>n/a</td>
<td>n/a</td>
</tr>
<tr>
<td>Arbitration</td>
<td>n/a</td>
<td>M</td>
<td>n/a</td>
<td>n/a</td>
</tr>
<tr>
<td>7-bit slave address</td>
<td>M</td>
<td>M</td>
<td>M</td>
<td>M</td>
</tr>
<tr>
<td>10-bit slave address</td>
<td>O</td>
<td>O</td>
<td>O</td>
<td></td>
</tr>
<tr>
<td>General Call address</td>
<td>O</td>
<td>O</td>
<td>O</td>
<td></td>
</tr>
<tr>
<td>Software Reset</td>
<td>O</td>
<td>O</td>
<td>O</td>
<td></td>
</tr>
<tr>
<td>START byte</td>
<td>n/a</td>
<td>O[3]</td>
<td>n/a</td>
<td></td>
</tr>
<tr>
<td>Device ID</td>
<td>n/a</td>
<td>n/a</td>
<td>O</td>
<td></td>
</tr>
</tbody>
</table>

[1] Also refers to a master acting as a slave.

[2] Clock stretching is a feature of some slaves. If no slaves in a system can stretch the clock (hold SCL LOW), the master need not be designed to handle this procedure.

[3] 'Bit banging' (software emulation) multi-master systems should consider a START byte. See Section 3.15.

### 3.1 SDA and SCL signals

Both SDA and SCL are bidirectional lines, connected to a positive supply voltage via a current-source or pull-up resistor (see Figure 3). When the bus is free, both lines are HIGH. The output stages of devices connected to the bus must have an open-drain or open-collector to perform the wired-AND function. Data on the I²C-bus can be transferred at rates of up to 100 kbit/s in the Standard-mode, up to 400 kbit/s in the Fast-mode, up to 1 Mbit/s in Fast-mode Plus, or up to 3.4 Mbit/s in the High-speed mode. The number of interfaces connected to the bus is limited by the bus capacitance.

For a single master application, the master’s SCL output can be a push-pull driver design provided that there are no devices on the bus which would stretch the clock.

![Diagram of SDA and SCL signals](image-url)

**Fig 3.** Devices with a variety of supply voltages sharing the same bus.

V\(_{\text{DD}2}\), V\(_{\text{DD}3}\) are device dependent (e.g., 12 V).
### 3.2 SDA and SCL logic levels

Due to the variety of different technology devices (CMOS, NMOS, bipolar) that can be connected to the I²C-bus, the levels of the logical '0' (LOW) and '1' (HIGH) are not fixed and depend on the associated level of $V_{DD}$. Input reference levels are set as 30 % and 70 % of $V_{DD}$; $V_{IL}$ is 0.3$V_{DD}$ and $V_{IH}$ is 0.7$V_{DD}$. See Figure 27, timing diagram. Some legacy device input levels were fixed at $V_{IL} = 1.5\, \text{V}$ and $V_{IH} = 3.0\, \text{V}$, but all new devices require this 30 %/70 % specification. See Section 6 for electrical specifications.

### 3.3 Data validity

The data on the SDA line must be stable during the HIGH period of the clock. The HIGH or LOW state of the data line can only change when the clock signal on the SCL line is LOW (see Figure 4). One clock pulse is generated for each data bit transferred.

![Figure 4. Bit transfer on the I²C-bus](mba607)

### 3.4 START and STOP conditions

All transactions begin with a START (S) and can be terminated by a STOP (P) (see Figure 5). A HIGH to LOW transition on the SDA line while SCL is HIGH defines a START condition. A LOW to HIGH transition on the SDA line while SCL is HIGH defines a STOP condition.

START and STOP conditions are always generated by the master. The bus is considered to be busy after the START condition. The bus is considered to be free again a certain time after the STOP condition. This bus free situation is specified in Section 6.

The bus stays busy if a repeated START (Sr) is generated instead of a STOP condition. In this respect, the START (S) and repeated START (Sr) conditions are functionally identical. For the remainder of this document, therefore, the S symbol will be used as a generic term to represent both the START and repeated START conditions, unless Sr is particularly relevant.

![Figure 5. START and STOP conditions](mba609)
Detection of START and STOP conditions by devices connected to the bus is easy if they incorporate the necessary interfacing hardware. However, microcontrollers with no such interface have to sample the SDA line at least twice per clock period to sense the transition.

3.5 Byte format

Every byte put on the SDA line must be 8 bits long. The number of bytes that can be transmitted per transfer is unrestricted. Each byte has to be followed by an Acknowledge bit. Data is transferred with the Most Significant Bit (MSB) first (see Figure 6). If a slave cannot receive or transmit another complete byte of data until it has performed some other function, for example servicing an internal interrupt, it can hold the clock line SCL LOW to force the master into a wait state. Data transfer then continues when the slave is ready for another byte of data and releases clock line SCL.

3.6 Acknowledge (ACK) and Not Acknowledge (NACK)

The acknowledge takes place after every byte. The acknowledge bit allows the receiver to signal the transmitter that the byte was successfully received and another byte may be sent. All clock pulses including the acknowledge 9th clock pulse are generated by the master.

The Acknowledge signal is defined as follows: the transmitter releases the SDA line during the acknowledge clock pulse so the receiver can pull the SDA line LOW and it remains stable LOW during the HIGH period of this clock pulse (see Figure 4). Set-up and hold times (specified in Section 6) must also be taken into account.

When SDA remains HIGH during this 9th clock pulse, this is defined as the Not Acknowledge signal. The master can then generate either a STOP condition to abort the transfer, or a repeated START condition to start a new transfer. There are five conditions that lead to the generation of a NACK:

1. No receiver is present on the bus with the transmitted address so there is no device to respond with an acknowledge.
2. The receiver is unable to receive or transmit because it’s performing some real-time function and is not ready to start communication with the master.
3. During the transfer the receiver gets data or commands that it does not understand.
4. During the transfer, the receiver cannot receive any more data bytes.
5. A master-receiver needs to signal the end of the transfer to the slave transmitter.
3.7 Clock synchronization

Two masters can begin transmitting on an idle bus at the same time and there needs to be a method for deciding which will take control of the bus and complete its transmission. This is done by clock synchronization and arbitration. In single master systems, clock synchronization and arbitration are not needed.

Clock synchronization is performed using the wired-AND connection of I²C interfaces to the SCL line. This means that a HIGH to LOW transition on the SCL line will cause the masters concerned to start counting off their LOW period and, once a master clock has gone LOW, it will hold the SCL line in that state until the clock HIGH state is reached (see Figure 7). However, the LOW to HIGH transition of this clock may not change the state of the SCL line if another clock is still within its LOW period. The SCL line will therefore be held LOW by the master with the longest LOW period. Masters with shorter LOW periods enter a HIGH wait-state during this time.

When all masters concerned have counted off their LOW period, the clock line will be released and go HIGH. There will then be no difference between the master clocks and the state of the SCL line, and all the masters will start counting their HIGH periods. The first master to complete its HIGH period will again pull the SCL line LOW.

In this way, a synchronized SCL clock is generated with its LOW period determined by the master with the longest clock LOW period, and its HIGH period determined by the one with the shortest clock HIGH period.

3.8 Arbitration

Arbitration, like synchronization, refers to a portion of the protocol required only if more than one master will be used in the system. Slaves are not involved in the arbitration procedure. A master may start a transfer only if the bus is free. Two masters may generate a START condition within the minimum hold time ($t_{HD,STA}$) of the START condition which results in a valid START condition on the bus. Arbitration is then required to determine which master will complete its transmission.

Arbitration proceeds bit by bit. During every bit, while SCL is HIGH, each master checks to see if the SDA level matches what it has sent. This process may take many bits. Two masters can actually complete an entire transaction without error, as long as the
transmissions are identical. The first time a master tries to send a HIGH, but detects that the SDA level is LOW, the master knows that it has lost the arbitration and will turn off its SDA output driver. The other master goes on to complete its transaction.

No information is lost during the arbitration process. A master that loses the arbitration can generate clock pulses until the end of the byte in which it loses the arbitration and must restart its transaction when the bus is idle.

If a master also incorporates a slave function and it loses arbitration during the addressing stage, it is possible that the winning master is trying to address it. The losing master must therefore switch over immediately to its slave mode.

Figure 8 shows the arbitration procedure for two masters. Of course, more may be involved depending on how many masters are connected to the bus. The moment there is a difference between the internal data level of the master generating DATA1 and the actual level on the SDA line, the DATA1 output is switched off. This will not affect the data transfer initiated by the winning master.

Since control of the I²C-bus is decided solely on the address and data sent by competing masters, there is no central master, nor any order of priority on the bus.

There is an undefined condition if the arbitration procedure is still in progress at the moment when one master sends a repeated START or a STOP condition while the other master is still sending data. In other words, the following combinations result in an undefined condition:

- Master 1 sends a repeated START condition and master 2 sends a data bit.
- Master 1 sends a STOP condition and master 2 sends a data bit.
- Master 1 sends a repeated START condition and master 2 sends a STOP condition.
3.9 Clock stretching

Clock stretching pauses a transaction by holding the SCL line LOW. The transaction cannot continue until the line is released HIGH again. Clock stretching is optional and in fact, most slave devices do not include an SCL driver so they are unable to stretch the clock.

On the byte level, a device may be able to receive bytes of data at a fast rate, but needs more time to store a received byte or prepare another byte to be transmitted. Slaves can then hold the SCL line LOW after reception and acknowledgment of a byte to force the master into a wait state until the slave is ready for the next byte transfer in a type of handshake procedure (see Figure 7).

On the bit level, a device such as a microcontroller with or without limited hardware for the I²C-bus, can slow down the bus clock by extending each clock LOW period. The speed of any master is thereby adapted to the internal operating rate of this device.

In Hs-mode, this handshake feature can only be used on byte level (see Section 5.3.2).

3.10 The slave address and R/W bit

Data transfers follow the format shown in Figure 9. After the START condition (S), a slave address is sent. This address is 7 bits long followed by an eighth bit which is a data direction bit (R/W)—a ‘zero’ indicates a transmission (WRITE), a ‘one’ indicates a request for data (READ) (refer to Figure 10). A data transfer is always terminated by a STOP condition (P) generated by the master. However, if a master still wishes to communicate on the bus, it can generate a repeated START condition (Sr) and address another slave without first generating a STOP condition. Various combinations of read/write formats are then possible within such a transfer.

![Fig 9. A complete data transfer](image)

![Fig 10. The first byte after the START procedure](image)
Possible data transfer formats are:

- Master-transmitter transmits to slave-receiver. The transfer direction is not changed (see Figure 11). The slave receiver acknowledges each byte.

- Master reads slave immediately after first byte (see Figure 12). At the moment of the first acknowledge, the master-transmitter becomes a master-receiver and the slave-receiver becomes a slave-transmitter. This first acknowledge is still generated by the slave. Subsequent acknowledges are generated by the master. The STOP condition is generated by the master, which sends a not-acknowledge (Ā) just prior to the STOP condition.

- Combined format (see Figure 13). During a change of direction within a transfer, the START condition and the slave address are both repeated, but with the R/W bit reversed. If a master-receiver sends a repeated START condition, it sends a not-acknowledge (Ā) just prior to the repeated START condition.

Notes:

1. Combined formats can be used, for example, to control a serial memory. During the first data byte, the internal memory location has to be written. After the START condition and slave address is repeated, data can be transferred.

2. All decisions on auto-increment or decrement of previously accessed memory locations, etc., are taken by the designer of the device.

3. Each byte is followed by an acknowledgment bit as indicated by the A or Ā blocks in the sequence.

4. I²C-bus compatible devices must reset their bus logic on receipt of a START or repeated START condition such that they all anticipate the sending of a slave address, even if these START conditions are not positioned according to the proper format.

5. A START condition immediately followed by a STOP condition (void message) is an illegal format. Many devices however are designed to operate properly under this condition.

6. Each device connected to the bus is addressable by a unique address. Normally a simple master/slave relationship exists, but it is possible to have multiple identical slaves that can receive and respond simultaneously, for example in a group broadcast. This technique works best when using bus switching devices like the PCA9546A where all four channels are on and identical devices are configured at the same time, understanding that it is impossible to determine that each slave acknowledges, and then turn on one channel at a time to read back each individual device’s configuration to confirm the programming. Refer to individual component data sheets.
3.11 10-bit addressing

10-bit addressing expands the number of possible addresses. Devices with 7-bit and 10-bit addresses can be connected to the same I²C-bus, and both 7-bit and 10-bit addressing can be used in all bus speed modes. Currently, 10-bit addressing is not being widely used.

The 10-bit slave address is formed from the first two bytes following a START condition (S) or a repeated START condition (Sr).

The first seven bits of the first byte are the combination 1111 0XX of which the last two bits (XX) are the two Most-Significant Bits (MSBs) of the 10-bit address; the eighth bit of the first byte is the R/W bit that determines the direction of the message.

Although there are eight possible combinations of the reserved address bits 1111 XXX, only the four combinations 1111 0XX are used for 10-bit addressing. The remaining four combinations 1111 1XX are reserved for future I²C-bus enhancements.
All combinations of read/write formats previously described for 7-bit addressing are possible with 10-bit addressing. Two are detailed here:

- **Master-transmitter transmits to slave-receiver with a 10-bit slave address.** The transfer direction is not changed (see Figure 14). When a 10-bit address follows a START condition, each slave compares the first seven bits of the first byte of the slave address (1111 0XX) with its own address and tests if the eighth bit (R/W direction bit) is 0. It is possible that more than one device will find a match and generate an acknowledge (A1). All slaves that found a match will compare the eight bits of the second byte of the slave address (XXXX XXXX) with their own addresses, but only one slave will find a match and generate an acknowledge (A2). The matching slave will remain addressed by the master until it receives a STOP condition (P) or a repeated START condition (Sr) followed by a different slave address.

- **Master-receiver reads slave-transmitter with a 10-bit slave address.** The transfer direction is changed after the second R/W bit (Figure 15). Up to and including acknowledge bit A2, the procedure is the same as that described for a master-transmitter addressing a slave-receiver. After the repeated START condition (Sr), a matching slave remembers that it was addressed before. This slave then checks if the first seven bits of the first byte of the slave address following Sr are the same as they were after the START condition (S), and tests if the eighth (R/W) bit is 1. If there is a match, the slave considers that it has been addressed as a transmitter and generates acknowledge A3. The slave-transmitter remains addressed until it receives a STOP condition (P) or until it receives another repeated START condition (Sr) followed by a different slave address. After a repeated START condition (Sr), all the other slave devices will also compare the first seven bits of the first byte of the slave address (1111 0XX) with their own addresses and test the eighth (R/W) bit. However, none of them will be addressed because R/W = 1 (for 10-bit devices), or the 1111 0XX slave address (for 7-bit devices) does not match.

Slave devices with 10-bit addressing will react to a ‘general call’ in the same way as slave devices with 7-bit addressing. Hardware masters can transmit their 10-bit address after a ‘general call’. In this case, the ‘general call’ address byte is followed by two successive bytes containing the 10-bit address of the master-transmitter. The format is as shown in Figure 15 where the first DATA byte contains the eight least-significant bits of the master address.
The START byte 0000 0001 (01h) can precede the 10-bit addressing in the same way as for 7-bit addressing (see Section 3.15).

### 3.12 Reserved addresses

Two groups of eight addresses (0000 XXX and 1111 XXX) are reserved for the purposes shown in Table 3.

<table>
<thead>
<tr>
<th>Slave address</th>
<th>R/W bit</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>0000 000</td>
<td>0</td>
<td>general call address[1]</td>
</tr>
<tr>
<td>0000 000</td>
<td>1</td>
<td>START byte[2]</td>
</tr>
<tr>
<td>0000 001</td>
<td>X</td>
<td>CBUS address[3]</td>
</tr>
<tr>
<td>0000 010</td>
<td>X</td>
<td>reserved for different bus format[4]</td>
</tr>
<tr>
<td>0000 011</td>
<td>X</td>
<td>reserved for future purposes</td>
</tr>
<tr>
<td>0000 1XX</td>
<td>X</td>
<td>Hs-mode master code</td>
</tr>
<tr>
<td>1111 1XX</td>
<td>X</td>
<td>reserved for future purposes</td>
</tr>
<tr>
<td>1111 0XX</td>
<td>X</td>
<td>10-bit slave addressing</td>
</tr>
</tbody>
</table>

[1] The general call address is used for several functions including software reset.
[2] No device is allowed to acknowledge at the reception of the START byte.
[3] The CBUS address has been reserved to enable the inter-mixing of CBUS compatible and I²C-bus compatible devices in the same system. I²C-bus compatible devices are not allowed to respond on reception of this address.
[4] The address reserved for a different bus format is included to enable I²C and other protocols to be mixed. Only I²C-bus compatible devices that can work with such formats and protocols are allowed to respond to this address.

Assignment of addresses within a local system is up to the system architect who must take into account the devices being used on the bus and any future interaction with other conventional I²C-buses. For example, a device with 7 user-assignable address pins allows all 128 addresses to be assigned. A reserved address can be used for a slave address if it is known that the reserved address is never going to be used for its intended purpose.

The I²C-bus committee coordinates allocation of I²C addresses. Further information can be obtained from the NXP web site [www.nxp.com/i2c](http://www.nxp.com/i2c).

### 3.13 General call address

The general call address is for addressing every device connected to the I²C-bus at the same time. However, if a device does not need any of the data supplied within the general call structure, it can ignore this address by not issuing an acknowledgment. If a device does require data from a general call address, it will acknowledge this address and behave as a slave-receiver. The master does not actually know how many devices acknowledged if one or more devices respond. The second and following bytes will be acknowledged by every slave-receiver capable of handling this data. A slave who cannot process one of these bytes must ignore it by not-acknowledging. Again, if one or more slaves acknowledge, the not-acknowledge will not be seen by the master. The meaning of the general call address is always specified in the second byte (see Figure 16).
There are two cases to consider:

- When the least significant bit B is a ‘zero’.
- When the least significant bit B is a ‘one’.

When bit B is a ‘zero’; the second byte has the following definition:

- 0000 0110 (06h): Reset and write programmable part of slave address by hardware. On receiving this 2-byte sequence, all devices designed to respond to the general call address will reset and take in the programmable part of their address. Precautions have to be taken to ensure that a device is not pulling down the SDA or SCL line after applying the supply voltage, since these low levels would block the bus.

- 0000 0100 (04h): Write programmable part of slave address by hardware. Behaves as above, but the device will not reset.

- 0000 0000 (00h): This code is not allowed to be used as the second byte.

Sequences of programming procedure are published in the appropriate device data sheets. The remaining codes have not been fixed and devices must ignore them.

When bit B is a ‘one’; the 2-byte sequence is a ‘hardware general call’. This means that the sequence is transmitted by a hardware master device, such as a keyboard scanner, which can be programmed to transmit a desired slave address. Since a hardware master does not know in advance to which device the message has to be transferred, it can only generate this hardware general call and its own address—identifying itself to the system (see Figure 17).

The seven bits remaining in the second byte contain the address of the hardware master. This address is recognized by an intelligent device (e.g., a microcontroller) connected to the bus which will then accept the information from the hardware master. If the hardware master can also act as a slave, the slave address is identical to the master address.

In some systems, an alternative could be that the hardware master transmitter is set in the slave-receiver mode after the system reset. In this way, a system configuring master can tell the hardware master-transmitter (which is now in slave-receiver mode) to which address data must be sent (see Figure 18). After this programming procedure, the hardware master remains in the master-transmitter mode.
3.14 Software reset

Following a General Call, (0000 0000), sending 0000 0110 (06h) as the second byte causes a software reset. This feature is optional and not all devices will respond to this command. On receiving this 2-byte sequence, all devices designed to respond to the general call address will reset and take in the programmable part of their address. Precautions have to be taken to ensure that a device is not pulling down the SDA or SCL line after applying the supply voltage, since these low levels would block the bus.

3.15 START byte

Microcontrollers can be connected to the I²C-bus in two ways. A microcontroller with an on-chip hardware I²C-bus interface can be programmed to be only interrupted by requests from the bus. When the device does not have such an interface, it must constantly monitor the bus via software. Obviously, the more times the microcontroller monitors, or polls the bus, the less time it can spend carrying out its intended function.

There is therefore a speed difference between fast hardware devices and a relatively slow microcontroller which relies on software polling.

In this case, data transfer can be preceded by a start procedure which is much longer than normal (see Figure 19). The start procedure consists of:

- A START condition (S)
- A START byte (0000 0001)
- An acknowledge clock pulse (ACK)
- A repeated START condition (Sr).
After the START condition $S$ has been transmitted by a master which requires bus access, the START byte (0000 0001) is transmitted. Another microcontroller can therefore sample the SDA line at a low sampling rate until one of the seven zeros in the START byte is detected. After detection of this LOW level on the SDA line, the microcontroller can switch to a higher sampling rate to find the repeated START condition $Sr$ which is then used for synchronization.

A hardware receiver will reset on receipt of the repeated START condition $Sr$ and will therefore ignore the START byte.

An acknowledge-related clock pulse is generated after the START byte. This is present only to conform with the byte handling format used on the bus. No device is allowed to acknowledge the START byte.

### 3.16 Bus clear

In the unlikely event where the clock (SCL) is stuck LOW, the preferential procedure is to reset the bus using the HW reset signal if your $I^2C$ devices have HW reset inputs. If the $I^2C$ devices do not have HW reset inputs, cycle power to the devices to activate the mandatory internal Power-On Reset (POR) circuit.

If the data line (SDA) is stuck LOW, the master should send 9 clock pulses. The device that held the bus LOW should release it sometime within those 9 clocks. If not, then use the HW reset or cycle power to clear the bus.

### 3.17 Device ID

The Device ID field (see Figure 20) is an optional 3 byte read-only (24 bits) word giving the following information:

- 12 bits with the manufacturer name, unique per manufacturer (e.g., NXP)
- 9 bits with the part identification, assigned by manufacturer (e.g., PCA9698)
- 3 bits with the die revision, assigned by manufacturer (e.g., RevX)
The Device ID is read-only, hard-wired in the device and can be accessed as follows:

1. START command
2. The master sends the Reserved Device ID I2C-bus address followed by the R/W bit set to ‘0’ (write): ‘1111 1000’.
3. The master sends the I2C-bus slave address of the slave device it needs to identify. The LSB is a ‘Don’t care’ value. Only one device must acknowledge this byte (the one that has the I2C-bus slave address).
4. The master sends a Re-START command.
   **Remark:** A STOP command followed by a START command will reset the slave state machine and the Device ID Read cannot be performed. Also, a STOP command or a Re-START command followed by an access to another slave device will reset the slave state machine and the Device ID Read cannot be performed.
5. The master sends the Reserved Device ID I2C-bus address followed by the R/W bit set to ‘1’ (read): ‘1111 1001’.
6. The Device ID Read can be done, starting with the 12 manufacturer bits (first byte + 4 MSBs of the second byte), followed by the 9 part identification bits (4 LSBs of the second byte + 5 MSBs of the third byte), and then the 3 die revision bits (3 LSBs of the third byte).
7. The master ends the reading sequence by NACKing the last byte, thus resetting the slave device state machine and allowing the master to send the STOP command.
   **Remark:** The reading of the Device ID can be stopped anytime by sending a NACK command.

If the master continues to ACK the bytes after the third byte, the slave rolls back to the first byte and keeps sending the Device ID sequence until a NACK has been detected.

Designers of new I2C devices who want to implement the device ID feature should contact NXP at i2c.support@nxp.com to have a unique manufacturer ID assigned.
4. Other uses of the I\textsuperscript{2}C-bus communications protocol

The I\textsuperscript{2}C-bus is used as the communications protocol for several system architectures. These architectures have added command sets and application-specific extensions in addition to the base I\textsuperscript{2}C specification. In general, simple I\textsuperscript{2}C-bus devices such as I/O extenders could be used in any one of these architectures since the protocol and physical interfaces are the same.

4.1 CBUS compatibility

CBUS receivers can be connected to the Standard-mode I\textsuperscript{2}C-bus. However, a third bus line called DLEN must then be connected and the acknowledge bit omitted. Normally, I\textsuperscript{2}C transmissions are sequences of 8-bit bytes; CBUS compatible devices have different formats.

In a mixed bus structure, I\textsuperscript{2}C-bus devices must not respond to the CBUS message. For this reason, a special CBUS address (0000 001X) to which no I\textsuperscript{2}C-bus compatible device will respond has been reserved. After transmission of the CBUS address, the DLEN line can be made active and a CBUS-format transmission sent. After the STOP condition, all devices are again ready to accept data.

Master-transmitters can send CBUS formats after sending the CBUS address. The transmission is ended by a STOP condition, recognized by all devices.

Remark: If the CBUS configuration is known, and expansion with CBUS compatible devices is not foreseen, the designer is allowed to adapt the hold time to the specific requirements of the device(s) used.

4.2 SMBus - System Management Bus

The SMBus uses I\textsuperscript{2}C hardware and I\textsuperscript{2}C hardware addressing, but adds second-level software for building special systems. In particular its specifications include an Address Resolution Protocol that can make dynamic address allocations.

Dynamic reconfiguration of the hardware and software allow bus devices to be ‘hot-plugged’ and used immediately, without restarting the system. The devices are recognized automatically and assigned unique addresses. This advantage results in a plug-and-play user interface. In both those protocols there is a very useful distinction made between a System Host and all the other devices in the system that can have the names and functions of masters or slaves.

SMBus is used today as a system management bus in most PCs. Developed by Intel and others in 1995, it modified some I\textsuperscript{2}C electrical and software characteristics for better compatibility with the quickly decreasing power supply budget of portable equipment. SMBus also has a ‘High Power’ version 2.0 that includes a 4 mA sink current that cannot be driven by I\textsuperscript{2}C chips unless the pull-up resistor is sized to I\textsuperscript{2}C-bus levels.

4.2.1 I\textsuperscript{2}C/SMBus compliancy

SMBus and I\textsuperscript{2}C protocols are basically the same: A SMBus master will be able to control I\textsuperscript{2}C devices and vice-versa at the protocol level. The SMBus clock is defined from 10 kHz to 100 kHz while I\textsuperscript{2}C can be 0 Hz to 100 kHz, 0 Hz to 400 kHz, 0 Hz to 1 MHz and 0 Hz to 3.4 MHz, depending on the mode. This means that an I\textsuperscript{2}C-bus running at less than 10 kHz will not be SMBus compliant since the SMBus devices may time out.
Logic levels are slightly different also: TTL for SMBus: LOW = 0.8 V and HIGH = 2.1 V, versus the 30%/70% V\textsubscript{DD} CMOS level for I\textsuperscript{2}C. This is not a problem if V\textsubscript{DD} > 3.0 V. If the I\textsuperscript{2}C device is below 3.0 V, then there could be a problem if the logic HIGH/LOW levels are not properly recognized.

### 4.2.2 Time-out feature

SMBus has a time-out feature which resets devices if a communication takes too long. This explains the minimum clock frequency of 10 kHz to prevent locking up the bus. I\textsuperscript{2}C can be a 'DC' bus, meaning that a slave device stretches the master clock when performing some routine while the master is accessing it. This will notify to the master that the slave is busy but does not want to lose the communication. The slave device will allow continuation after its task is complete. There is no limit in the I\textsuperscript{2}C-bus protocol as to how long this delay can be, whereas for a SMBus system, it would be limited to 35 ms.

SMBus protocol just assumes that if something takes too long, then it means that there is a problem on the bus and that all devices must reset in order to clear this mode. Slave devices are not then allowed to hold the clock LOW too long.

### 4.2.3 Differences between SMBus 1.0 and SMBus 2.0

The SMBus specification defines two classes of electrical characteristics: low power and high power. The first class, originally defined in the SMBus 1.0 and 1.1 specifications, was designed primarily with Smart Batteries in mind, but could be used with other low-power devices.

The 2.0 version introduces an alternative higher power set of electrical characteristics. This class is appropriate for use when higher drive capability is required, for example with SMBus devices on PCI add-in cards and for connecting such cards across the PCI connector between each other and to SMBus devices on the system board.

Devices may be powered by the bus V\textsubscript{DD} or by another power source, V\textsubscript{Bus}, (as with, for example, Smart Batteries) and will inter-operate as long as they adhere to the SMBus electrical specifications for their class.

NXP devices have a higher power set of electrical characteristics than SMBus 1.0. The main difference is the current sink capability with V\textsubscript{OL} = 0.4 V.

- SMBus low power = 350 μA
- SMBus high power = 4 mA
- I\textsuperscript{2}C-bus = 3 mA

SMBus ‘high power’ devices and I\textsuperscript{2}C-bus devices will work together if the pull-up resistor is sized for 3 mA.

For more information, refer to: [www.nxp.com/redirect/smbus.org](http://www.nxp.com/redirect/smbus.org).
4.3 PMBus - Power Management Bus

PMBus is a standard way to communicate between power converters and a system host over the SMBus to provide more intelligent control of the power converters. The PMBus specification defines a standard set of device commands so that devices from multiple sources will function identically. PMBus devices will use the SMBus Version 1.1 plus extensions for transport.

For more information, refer to: www.nxp.com/redirect/pmbus.org.

4.4 Intelligent Platform Management Interface (IPMI)

Intelligent Platform Management Interface (IPMI) defines a standardized, abstracted, message-based interface for intelligent platform management hardware. IPMI also defines standardized records for describing platform management devices and their characteristics. IPMI increases reliability of systems by monitoring parameters such as temperatures, voltages, fans and chassis intrusion.

IPMI provides general system management functions such as automatic alerting, automatic system shutdown and re-start, remote re-start and power control. The standardized interface to intelligent platform management hardware aids in prediction and early monitoring of hardware failures as well as diagnosis of hardware problems.

This standardized bus and protocol for extending management control, monitoring, and event delivery within the chassis:

- I²C based
- Multi-master
- Simple Request/Response Protocol
- Uses IPMI Command sets
- Supports non-IPMI devices
- Physically I²C but write-only (master capable devices); hot swap not required
- Enables the Baseboard Management Controller (BMC) to accept IPMI request messages from other management controllers in the system
- Allows non-intelligent devices as well as management controllers on the bus
- BMC serves as a controller to give system software access to IPMB.

Hardware implementation is isolated from software implementation so that new sensors and events can then be added without any software changes.

For more information, refer to: www.nxp.com/redirect/intel.com/design/servers/ipmi.
4.5 Advanced Telecom Computing Architecture (ATCA)

Advanced Telecom Computing Architecture (ATCA) is a follow-on to Compact PCI (cPCI), providing a standardized form-factor with larger card area, larger pitch and larger power supply for use in advanced rack-mounted telecom hardware. It includes a fault-tolerant scheme for thermal management that uses I²C-bus communications between boards.

Advanced Telecom Computing Architecture (ATCA) is being backed by more than 100 companies including many of the large players such as Intel, Lucent, and Motorola.

There are two general compliant approaches to an ATCA compliant fan control: the first is an Intelligent FRU (Field Replaceable Unit) which means that the fan control would be directly connected to the IPMB (Intelligent Platform Management Bus); the second is a Managed or Non-intelligent FRU.

One requirement is the inclusion of hardware and software to manage the dual I²C-buses. This requires an on-board isolated supply to power the circuitry, a buffered dual I²C-bus with rise time accelerators, and 3-state capability. The I²C controller must be able to support a multi-master I²C dual bus and handle the standard set of fan commands outlined in the protocol. In addition, on-board temperature reporting, tray capability reporting, fan turn-off capabilities, and non-volatile storage are required.

For more information, refer to: [www.nxp.com/redirect/picmg.org/v2internal/newinitiative](http://www.nxp.com/redirect/picmg.org/v2internal/newinitiative).

5. Bus speeds

Originally, the I²C-bus was limited to 100 kbit/s operation. Over time there have been several additions to the specification so that there are now 4 operating speed categories. All devices are downward-compatible—any device may be operated at a lower bus speed.

- **Standard-mode (Sm)**, with a bit rate up to 100 kbit/s
- **Fast-mode (Fm)**, with a bit rate up to 400 kbit/s
- **Fast-mode Plus (Fm+)**, with a bit rate up to 1 Mbit/s
- **High-speed mode (Hs-mode)**, with a bit rate up to 3.4 Mbit/s.

5.1 Fast-mode

Fast-mode devices can receive and transmit at up to 400 kbit/s. The minimum requirement is that they can synchronize with a 400 kbit/s transfer; they can then prolong the LOW period of the SCL signal to slow down the transfer. The protocol, format, logic levels and maximum capacitive load for the SDA and SCL lines are the same as the Standard-mode I²C-bus specification. Fast-mode devices are downward-compatible and can communicate with Standard-mode devices in a 0 to 100 kbit/s I²C-bus system. As Standard-mode devices, however, are not upward compatible; they should not be incorporated in a Fast-mode I²C-bus system as they cannot follow the higher transfer rate and unpredictable states would occur.

The Fast-mode I²C-bus specification has the following additional features compared with the Standard-mode:

The maximum bit rate is increased to 400 kbit/s.
Timing of the serial data (SDA) and serial clock (SCL) signals has been adapted. There is no need for compatibility with other bus systems such as CBUS because they cannot operate at the increased bit rate.

The inputs of Fast-mode devices incorporate spike suppression and a Schmitt trigger at the SDA and SCL inputs.

The output buffers of Fast-mode devices incorporate slope control of the falling edges of the SDA and SCL signals.

If the power supply to a Fast-mode device is switched off, the SDA and SCL I/O pins must be floating so that they do not obstruct the bus lines.

The external pull-up devices connected to the bus lines must be adapted to accommodate the shorter maximum permissible rise time for the Fast-mode I²C-bus. For bus loads up to 200 pF, the pull-up device for each bus line can be a resistor; for bus loads between 200 pF and 400 pF, the pull-up device can be a current source (3 mA max.) or a switched resistor circuit (see Section 7.2.4).

### 5.2 Fast-mode Plus

Fast-mode Plus (Fm+) devices offer an increase in I²C-bus transfer speeds and total bus capacitance. Fm+ devices can transfer information at bit rates of up to 1 Mbit/s, yet they remain fully downward compatible with Fast- or Standard-mode devices for bidirectional communication in a mixed-speed bus system. The same serial bus protocol and data format is maintained as with the Fast- or Standard-mode system. Fm+ devices also offer increased drive current over Fast- or Standard-mode devices allowing them to drive longer and/or more heavily loaded buses so that bus buffers do not need to be used.

The drivers in Fast-mode Plus parts are strong enough to satisfy the Fast-mode Plus timing specification with the same 400 pF load as Standard-mode parts. They are also tolerant of the 1 µs rise time of Standard-mode parts in order to be backward compatible with Standard-mode. In applications where only Fast-mode Plus parts are present, the high drive strength and tolerance for slow rise and fall times allow the use of larger bus capacitance as long as set-up, minimum LOW time and minimum HIGH time for Fast-mode Plus are all satisfied and the fall time and rise time do not exceed the 300 ns t_f and 1 µs t_r specifications of Standard-mode. Bus speed can be traded against load capacitance to increase the maximum capacitance by about a factor of 10.

### 5.3 Hs-mode

High-speed mode (Hs-mode) devices offer a quantum leap in I²C-bus transfer speeds. Hs-mode devices can transfer information at bit rates of up to 3.4 Mbit/s, yet they remain fully downward compatible with Fast-mode Plus, Fast- or Standard-mode (F/S) devices for bidirectional communication in a mixed-speed bus system. With the exception that arbitration and clock synchronization is not performed during the Hs-mode transfer, the same serial bus protocol and data format is maintained as with the F/S-mode system.
5.3.1 High speed transfer
To achieve a bit transfer of up to 3.4 Mbit/s the following improvements have been made to the regular I^2C-bus specification:

- Hs-mode master devices have an open-drain output buffer for the SDAH signal and a combination of an open-drain pull-down and current-source pull-up circuit on the SCLH output. This current-source circuit shortens the rise time of the SCLH signal. Only the current-source of one master is enabled at any one time, and only during Hs-mode.

- No arbitration or clock synchronization is performed during Hs-mode transfer in multi-master systems, which speeds-up bit handling capabilities. The arbitration procedure always finishes after a preceding master code transmission in F/S-mode.

- Hs-mode master devices generate a serial clock signal with a HIGH to LOW ratio of 1 to 2. This relieves the timing requirements for set-up and hold times.

- As an option, Hs-mode master devices can have a built-in bridge. During Hs-mode transfer, the high-speed data (SDAH) and high-speed serial clock (SCLH) lines of Hs-mode devices are separated by this bridge from the SDA and SCL lines of F/S-mode devices. This reduces the capacitive load of the SDAH and SCLH lines resulting in faster rise and fall times.

- The only difference between Hs-mode slave devices and F/S-mode slave devices is the speed at which they operate. Hs-mode slaves have open-drain output buffers on the SCLH and SDAH outputs. Optional pull-down transistors on the SCLH pin can be used to stretch the LOW level of the SCLH signal, although this is only allowed after the acknowledge bit in Hs-mode transfers.

- The inputs of Hs-mode devices incorporate spike suppression and a Schmitt trigger at the SDAH and SCLH inputs.

- The output buffers of Hs-mode devices incorporate slope control of the falling edges of the SDAH and SCLH signals.

Figure 21 shows the physical I^2C-bus configuration in a system with only Hs-mode devices. Pins SDA and SCL on the master devices are only used in mixed-speed bus systems and are not connected in an Hs-mode only system. In such cases, these pins can be used for other functions.

Optional series resistors R_s protect the I/O stages of the I^2C-bus devices from high-voltage spikes on the bus lines and minimize ringing and interference.

Pull-up resistors R_p maintain the SDAH and SCLH lines at a HIGH level when the bus is free and ensure the signals are pulled up from a LOW to a HIGH level within the required rise time. For higher capacitive bus-line loads (>100 pF), the resistor R_p can be replaced by external current-source pull-ups to meet the rise time requirements. Unless proceeded by an acknowledge bit, the rise time of the SCLH clock pulses in Hs-mode transfers is shortened by the internal current-source pull-up circuit MCS of the active master.
5.3.2 Serial data format in Hs-mode

Serial data transfer format in Hs-mode meets the Standard-mode \( \text{I}^2\text{C} \)-bus specification. Hs-mode can only commence after the following conditions (all of which are in F/S-mode):

1. START condition (S)
2. 8-bit master code (0000 1XXX)
3. Not-acknowledge bit (\( \bar{A} \))

Figure 22 and Figure 23 show this in more detail. This master code has two main functions:

- It allows arbitration and synchronization between competing masters at F/S-mode speeds, resulting in one winning master.
- It indicates the beginning of an Hs-mode transfer.

Hs-mode master codes are reserved 8-bit codes, which are not used for slave addressing or other purposes. Furthermore, as each master has its own unique master code, up to eight Hs-mode masters can be present on the one \( \text{I}^2\text{C} \)-bus system (although master code 0000 1000 should be reserved for test and diagnostic purposes). The master code for an Hs-mode master device is software programmable and is chosen by the System Designer.
Arbitration and clock synchronization only take place during the transmission of the master code and not-acknowledge bit (\(\bar{A}\)), after which one winning master remains active. The master code indicates to other devices that an Hs-mode transfer is to begin and the connected devices must meet the Hs-mode specification. As no device is allowed to acknowledge the master code, the master code is followed by a not-acknowledge (\(\bar{A}\)).

After the not-acknowledge bit (\(\bar{A}\)), and the SCLH line has been pulled-up to a HIGH level, the active master switches to Hs-mode and enables (at time \(t_{H}\), see Figure 23) the current-source pull-up circuit for the SCLH signal. As other devices can delay the serial transfer before \(t_{H}\) by stretching the LOW period of the SCLH signal, the active master will enable its current-source pull-up circuit when all devices have released the SCLH line and the SCLH signal has reached a HIGH level, thus speeding up the last part of the rise time of the SCLH signal.

The active master then sends a repeated START condition (Sr) followed by a 7-bit slave address (or 10-bit slave address, see Section 3.11) with a R/W bit address, and receives an acknowledge bit (A) from the selected slave.

After a repeated START condition and after each acknowledge bit (A) or not-acknowledge bit (\(\bar{A}\)), the active master disables its current-source pull-up circuit. This enables other devices to delay the serial transfer by stretching the LOW period of the SCLH signal. The active master re-enables its current-source pull-up circuit again when all devices have released and the SCLH signal reaches a HIGH level, and so speeds up the last part of the SCLH signal’s rise time.

Data transfer continues in Hs-mode after the next repeated START (Sr), and only switches back to F/S-mode after a STOP condition (P). To reduce the overhead of the master code, it is possible that a master links a number of Hs-mode transfers, separated by repeated START conditions (Sr).

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**Fig 22. Data transfer format in Hs-mode**
5.3.3 Switching from F/S-mode to Hs-mode and back

After reset and initialization, Hs-mode devices must be in Fast-mode (which is in effect F/S-mode, as Fast-mode is downward compatible with Standard-mode). Each Hs-mode device can switch from Fast-mode to Hs-mode and back and is controlled by the serial transfer on the I²C-bus.

Before time $t_1$ in Figure 23, each connected device operates in Fast-mode. Between times $t_1$ and $t_H$ (this time interval can be stretched by any device) each connected device must recognize the ‘$S$ 00001XXX $A$’ sequence and has to switch its internal circuit from the Fast-mode setting to the Hs-mode setting. Between times $t_1$ and $t_H$ the connected master and slave devices perform this switching by the following actions.

The active (winning) master:

1. Adapts its SDAH and SCLH input filters according to the spike suppression requirement in Hs-mode.
2. Adapts the set-up and hold times according to the Hs-mode requirements.
3. Adapts the slope control of its SDAH and SCLH output stages according to the Hs-mode requirement.
4. Switches to the Hs-mode bit-rate, which is required after time $t_H$.
5. Enables the current source pull-up circuit of its SCLH output stage at time $t_H$.
The non-active, or losing masters:

1. Adapt their SDAH and SCLH input filters according to the spike suppression requirement in Hs-mode.
2. Wait for a STOP condition to detect when the bus is free again.

All slaves:

1. Adapt their SDAH and SCLH input filters according to the spike suppression requirement in Hs-mode.
2. Adapt the set-up and hold times according to the Hs-mode requirements. This requirement may already be fulfilled by the adaptation of the input filters.
3. Adapt the slope control of their SDAH output stages, if necessary. For slave devices, slope control is applicable for the SDAH output stage only and, depending on circuit tolerances, both the Fast-mode and Hs-mode requirements may be fulfilled without switching its internal circuit.

At time $t_{FS}$ in Figure 23, each connected device must recognize the STOP condition (P) and switch its internal circuit from the Hs-mode setting back to the Fast-mode setting as present before time $t_{1}$. This must be completed within the minimum bus free time as specified in Table 6 according to the Fast-mode specification.

**5.3.4 Hs-mode devices at lower speed modes**

Hs-mode devices are fully downwards compatible, and can be connected to an F/S-mode I$_2$C-bus system (see Figure 24). As no master code will be transmitted in such a configuration, all Hs-mode master devices stay in F/S-mode and communicate at F/S-mode speeds with their current-source disabled. The SDAH and SCLH pins are used to connect to the F/S-mode bus system, allowing the SDA and SCL pins (if present) on the Hs-mode master device to be used for other functions.
5.3.5 Mixed speed modes on one serial bus system

If a system has a combination of Hs-mode, Fast-mode and/or Standard-mode devices, it is possible, by using an interconnection bridge, to have different bit rates between different devices (see Figure 25 and Figure 26).

One bridge is required to connect/disconnect an Hs-mode section to/from an F/S-mode section at the appropriate time. This bridge includes a level shift function that allows devices with different supply voltages to be connected. For example F/S-mode devices with a $V_{DD2}$ of 5 V can be connected to Hs-mode devices with a $V_{DD1}$ of 3 V or less (i.e., where $V_{DD2} \geq V_{DD1}$), provided SDA and SCL pins are 5 V tolerant. This bridge is incorporated in Hs-mode master devices and is completely controlled by the serial signals SDAH, SCLH, SDA and SCL. Such a bridge can be implemented in any IC as an autonomous circuit.

TR1, TR2 and TR3 are N-channel transistors. TR1 and TR2 have a transfer gate function, and TR3 is an open-drain pull-down stage. If TR1 or TR2 are switched on they transfer a LOW level in both directions, otherwise when both the drain and source rise to a HIGH level there will be a high-impedance between the drain and source of each switched-on transistor. In the latter case, the transistors will act as a level shifter as SDAH and SCLH will be pulled-up to $V_{DD1}$ and SDA and SCL will be pulled-up to $V_{DD2}$.

During F/S-mode speed, a bridge on one of the Hs-mode masters connects the SDAH and SCLH lines to the corresponding SDA and SCL lines thus permitting Hs-mode devices to communicate with F/S-mode devices at slower speeds. Arbitration and synchronization is possible during the total F/S-mode transfer between all connected devices as described in Section 3.7.
to separate the two bus sections and allows Hs-mode devices to communicate with each other at 3.4 Mbit/s. Arbitration between Hs-mode devices and F/S-mode devices is only performed during the master code (0000 1XXX), and normally won by one Hs-mode master as no slave address has four leading zeros. Other masters can win the arbitration only if they send a reserved 8-bit code (0000 0XXX). In such cases, the bridge remains closed and the transfer proceeds in F/S-mode. Table 4 gives the possible communication speeds in such a system.

Table 4. Communication bit rates in a mixed-speed bus system

<table>
<thead>
<tr>
<th>Transfer between</th>
<th>Serial bus system configuration</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Hs + Fast + Standard</td>
</tr>
<tr>
<td>Hs ↔ Hs</td>
<td>0 to 3.4 Mbit/s</td>
</tr>
<tr>
<td>Hs ↔ Fast</td>
<td>0 to 100 kbit/s</td>
</tr>
<tr>
<td>Hs ↔ Standard</td>
<td>0 to 100 kbit/s</td>
</tr>
<tr>
<td>Fast ↔ Standard</td>
<td>0 to 100 kbit/s</td>
</tr>
<tr>
<td>Fast ↔ Fast</td>
<td>0 to 100 kbit/s</td>
</tr>
<tr>
<td>Standard ↔ Standard</td>
<td>0 to 100 kbit/s</td>
</tr>
</tbody>
</table>

Remark: Table 4 assumes that the Hs devices are isolated from the Fm and Sm devices when operating at 3.4 Mbit/s. The bus speed is always constrained to the maximum communication rate of the slowest device attached to the bus.
5.3.6 Standard, Fast-mode and Fast-mode Plus transfer in a mixed-speed bus system

The bridge shown in Figure 25 interconnects corresponding serial bus lines, forming one serial bus system. As no master code (0000 1XXX) is transmitted, the current-source pull-up circuits stay disabled and all output stages are open-drain. All devices, including Hs-mode devices, communicate with each other according the protocol, format and speed of the F/S-mode I\textsuperscript{2}C-bus specification.

5.3.7 Hs-mode transfer in a mixed-speed bus system

Figure 26 shows the timing diagram of a complete Hs-mode transfer, which is invoked by a START condition, a master code, and a not-acknowledge \textbar (at F/S-mode speed). Although this timing diagram is split in two parts, it should be viewed as one timing diagram were time point \( t_{H} \) is a common point for both parts.

The master code is recognized by the bridge in the active or non-active master (see Figure 25). The bridge performs the following actions:

1. Between \( t_{1} \) and \( t_{H} \) (see Figure 26), transistor TR1 opens to separate the SDAH and SDA lines, after which transistor TR3 closes to pull-down the SDA line to \( V_{SS} \).
2. When both SCLH and SCL become HIGH (\( t_{H} \) in Figure 26), transistor TR2 opens to separate the SCLH and SCL lines. TR2 must be opened before SCLH goes LOW after Sr.

Hs-mode transfer starts after \( t_{H} \) with a repeated START condition (Sr). During Hs-mode transfer, the SCL line stays at a HIGH and the SDA line at a LOW steady-state level, and so is prepared for the transfer of a STOP condition (P).

After each acknowledge (A) or not-acknowledge bit (\textbar\textbar), the active master disables its current-source pull-up circuit. This enables other devices to delay the serial transfer by stretching the LOW period of the SCLH signal. The active master re-enables its current-source pull-up circuit again when all devices are released and the SCLH signal reaches a HIGH level, and so speeds up the last part of the SCLH signal's rise time. In irregular situations, F/S-mode devices can close the bridge (TR1 and TR2 closed, TR3 open) at any time by pulling down the SCL line for at least 1 \( \mu \)s, e.g., to recover from a bus hang-up.

Hs-mode finishes with a STOP condition and brings the bus system back into the F/S-mode. The active master disables its current-source MCS when the STOP condition (P) at SDAH is detected (\( t_{FS} \) in Figure 26). The bridge also recognizes this STOP condition and takes the following actions:

1. Transistor TR2 closes after \( t_{FS} \) to connect SCLH with SCL; both of which are HIGH at this time. Transistor TR3 opens after \( t_{FS} \), which releases the SDA line and allows it to be pulled HIGH by the pull-up resistor \( R_{P} \). This is the STOP condition for the F/S-mode devices. TR3 must open fast enough to ensure the bus free time between the STOP condition and the earliest next START condition is according to the Fast-mode specification (see \( t_{BUF} \) in Table 6).
2. When SDA reaches a HIGH (\( t_{2} \) in Figure 26) transistor TR1 closes to connect SDAH with SDA. (Note: interconnections are made when all lines are HIGH, thus preventing spikes on the bus lines.) TR1 and TR2 must be closed within the minimum bus free time according to the Fast-mode specification (see \( t_{BUF} \) in Table 6).
5.3.8 Timing requirements for the bridge in a mixed-speed bus system

It can be seen from Figure 26 that the actions of the bridge at $t_1$, $t_H$, and $t_{FS}$ must be so fast that it does not affect the SDAH and SCLH lines. Furthermore the bridge must meet the related timing requirements of the Fast-mode specification for the SDA and SCL lines.
6. Electrical specifications and timing for I/O stages and bus lines

6.1 Standard-, Fast-, and Fast-mode Plus devices

The I/O levels, I/O current, spike suppression, output slope control and pin capacitance are given in Table 5. The I^2C-bus timing characteristics, bus-line capacitance and noise margin are given in Table 6. Figure 27 shows the timing definitions for the I^2C-bus.

The minimum HIGH and LOW periods of the SCL clock specified in Table 6 determine the maximum bit transfer rates of 100 kbit/s for Standard-mode devices, 400 kbit/s for Fast-mode devices, and 1000 kbits/s for Fast-mode Plus. Devices must be able to follow transfers at their own maximum bit rates, either by being able to transmit or receive at that speed or by applying the clock synchronization procedure described in Section 3.7 which will force the master into a wait state and stretch the LOW period of the SCL signal. Of course, in the latter case the bit transfer rate is reduced.

Table 5. Characteristics of the SDA and SCL I/O stages

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Standard-mode</th>
<th>Fast-mode</th>
<th>Fast-mode Plus</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td></td>
<td>Min</td>
<td>Max</td>
<td>Min</td>
<td>Max</td>
</tr>
<tr>
<td>V_{IL}</td>
<td>LOW-level input voltage</td>
<td></td>
<td>-0.5</td>
<td>0.3V_{DD}</td>
<td>-0.5</td>
<td>0.3V_{DD}</td>
</tr>
<tr>
<td>V_{IH}</td>
<td>HIGH-level input voltage</td>
<td></td>
<td>0.7V_{DD}</td>
<td>[2]</td>
<td>0.7V_{DD}</td>
<td>[2]</td>
</tr>
<tr>
<td>V_{hys}</td>
<td>hysteresis of Schmitt trigger inputs</td>
<td>V_{DD} &gt; 2 V</td>
<td>n/a</td>
<td>n/a</td>
<td>0.05V_{DD}</td>
<td>-</td>
</tr>
<tr>
<td></td>
<td></td>
<td>V_{DD} &lt; 2 V</td>
<td>n/a</td>
<td>n/a</td>
<td>0.1V_{DD}</td>
<td>-</td>
</tr>
<tr>
<td>V_{OL1}</td>
<td>LOW-level output voltage (open-drain or open-collector) at 3 mA sink current</td>
<td>V_{DD} &gt; 2 V</td>
<td>0</td>
<td>0.4</td>
<td>0</td>
<td>0.4</td>
</tr>
<tr>
<td>V_{OL3}</td>
<td>LOW-level output voltage (open-drain or open-collector) at 3 mA sink current</td>
<td>V_{DD} &lt; 2 V</td>
<td>n/a</td>
<td>n/a</td>
<td>0</td>
<td>0.2V_{DD}</td>
</tr>
<tr>
<td>I_{OL}</td>
<td>LOW-level output current</td>
<td>V_{OL} = 0.4 V</td>
<td>3</td>
<td>n/a</td>
<td>3</td>
<td>n/a</td>
</tr>
<tr>
<td></td>
<td></td>
<td>V_{OL} = 0.6 V[4]</td>
<td>n/a</td>
<td>n/a</td>
<td>6</td>
<td>-</td>
</tr>
<tr>
<td>t_{of}</td>
<td>output fall time from V_{IH}max to V_{IL}max</td>
<td></td>
<td>-</td>
<td>250[4]</td>
<td>20 + 0.1C_{[3]}</td>
<td>250[4]</td>
</tr>
<tr>
<td>t_{SP}</td>
<td>pulse width of spikes that must be suppressed by the input filter</td>
<td></td>
<td>n/a</td>
<td>n/a</td>
<td>0</td>
<td>50[6]</td>
</tr>
<tr>
<td>I_{i}</td>
<td>input current each I/O pin</td>
<td>0.1V_{DD} &lt; V_{i} &lt; 0.9V_{DD_{max}}</td>
<td>-10</td>
<td>+10</td>
<td>-10[5]</td>
<td>+10[5]</td>
</tr>
<tr>
<td>C_{i}</td>
<td>capacitance for each I/O pin</td>
<td>[6]</td>
<td>10</td>
<td>-</td>
<td>10</td>
<td>-</td>
</tr>
</tbody>
</table>

[1] Some legacy Standard-mode devices had fixed input levels of V_{IL} = 1.5 V and V_{IH} = 3.0 V. Refer to component data sheets.
[2] Maximum V_{IH} = V_{DD_{max}} + 0.5 V or 5.5 V, whichever is lower. See component data sheets.
[3] C_{a} = capacitance of one bus line in pF.
[4] The maximum t_{of} for the SDA and SCL bus lines quoted in Table 6 (300 ns) is longer than the specified maximum t_{of} for the output stages (250 ns). This allows series protection resistors (R_{s}) to be connected between the SDA/SCL pins and the SDA/SCL bus lines as shown in Figure 33 without exceeding the maximum specified t_{of}.
[5] I/O pins of Fast-mode and Fast-mode Plus devices must not obstruct the SDA and SCL lines if V_{DD} is switched off.
[6] Input filters on the SDA and SCL inputs suppress noise spikes of less than 50 ns.
In Fast-mode Plus, fall time is specified the same for both output stage and bus timing. If series resistors are used, designers should allow for this when considering bus timing.

Special purpose devices such as multiplexers and switches may exceed this capacitance due to the fact that they connect multiple paths together.

In order to drive full bus load at 400 kHz, 6 mA $I_{OL}$ is required at 0.6 V $V_{OL}$. Parts not meeting this specification can still function, but not at 400 kHz and 400 pF.

Table 6. Characteristics of the SDA and SCL bus lines for Standard, Fast, and Fast-mode Plus $I^2C$-bus devices

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Standard-mode</th>
<th>Fast-mode</th>
<th>Fast-mode Plus</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$f_{SCL}$</td>
<td>SCL clock frequency</td>
<td></td>
<td>0</td>
<td>Max</td>
<td>Min</td>
<td>Max</td>
</tr>
<tr>
<td>$t_{HD;STA}$</td>
<td>hold time (repeated) START condition</td>
<td>After this period, the first clock pulse is generated.</td>
<td>4.0</td>
<td>-</td>
<td>0.6</td>
<td>-</td>
</tr>
<tr>
<td>$t_{LOW}$</td>
<td>LOW period of the SCL clock</td>
<td></td>
<td>4.7</td>
<td>-</td>
<td>1.3</td>
<td>-</td>
</tr>
<tr>
<td>$t_{HIGH}$</td>
<td>HIGH period of the SCL clock</td>
<td></td>
<td>4.0</td>
<td>-</td>
<td>0.6</td>
<td>-</td>
</tr>
<tr>
<td>$t_{SU;STA}$</td>
<td>set-up time for a repeated START condition</td>
<td></td>
<td>4.7</td>
<td>-</td>
<td>0.6</td>
<td>-</td>
</tr>
<tr>
<td>$t_{HD;DAT}$</td>
<td>data hold time</td>
<td>CBUS compatible masters (see Remark in Section 4.1)</td>
<td>5.0</td>
<td>-</td>
<td>-</td>
<td>-</td>
</tr>
<tr>
<td>$t_{BUF}$</td>
<td>bus free time between a STOP and START condition</td>
<td></td>
<td>0</td>
<td>-</td>
<td>100[5]</td>
<td>-</td>
</tr>
<tr>
<td>$C_b$</td>
<td>capacitive load for each bus line</td>
<td></td>
<td>-</td>
<td>400</td>
<td>-</td>
<td>400</td>
</tr>
<tr>
<td>$V_{nL}$</td>
<td>noise margin at the LOW level</td>
<td>for each connected device (including hysteresis)</td>
<td>0.1$V_{DD}$</td>
<td>-</td>
<td>0.1$V_{DD}$</td>
<td>-</td>
</tr>
<tr>
<td>$V_{nH}$</td>
<td>noise margin at the HIGH level</td>
<td>for each connected device (including hysteresis)</td>
<td>0.2$V_{DD}$</td>
<td>-</td>
<td>0.2$V_{DD}$</td>
<td>-</td>
</tr>
</tbody>
</table>

[1] All values referred to $V_{IH(min)}$ (0.3$V_{DD}$) and $V_{IL(max)}$ (0.7$V_{DD}$) levels (see Table 5).

[2] $t_{HD;DAT}$ is the data hold time that is measured from the falling edge of SCL, applies to data in transmission and the acknowledge.
[3] A device must internally provide a hold time of at least 300 ns for the SDA signal (with respect to the \( V_{I(H(min)} \) of the SCL signal) to bridge the undefined region of the falling edge of SCL.

[4] The maximum \( t_{HD;DAT} \) could be 3.45 \( \mu \)s and 0.9 \( \mu \)s for Standard-mode and Fast-mode, but must be less than the maximum of \( t_{VD;DAT} \) or \( t_{VD;ACK} \) by a transition time. This maximum must only be met if the device does not stretch the LOW period \( (t_{LOW}) \) of the SCL signal. If the clock stretches the SCL, the data must be valid by the set-up time before it releases the clock.

[5] A Fast-mode \( \text{I}^2\text{C} \)-bus device can be used in a Standard-mode \( \text{I}^2\text{C} \)-bus system, but the requirement \( t_{SU;DAT} \) 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line \( t_{(max)} + t_{SU;DAT} = 1000 + 250 = 1250 \) ns (according to the Standard-mode \( \text{I}^2\text{C} \)-bus specification) before the SCL line is released. Also the acknowledge timing must meet this set-up time.

[6] \( C_{B} \) = total capacitance of one bus line in pF. If mixed with Hs-mode devices, faster fall times according to Table 6 are allowed.

[7] The maximum \( t_{r} \) for the SDA and SCL bus lines is specified at 300 ns. The maximum fall time for the SDA output stage \( t_{f} \) is specified at 250 ns. This allows series protection resistors to be connected in between the SDA and the SCL pins and the SDA/SCL bus lines without exceeding the maximum specified \( t_{r} \).

[8] In Fast-mode Plus, fall time is specified the same for both output stage and bus timing. If series resistors are used, designers should allow for this when considering bus timing.

[9] The maximum bus capacitance allowable may vary from this value depending on the actual operating voltage and frequency of the application. Section 7.2 discusses techniques for coping with higher bus capacitances.

[10] \( t_{VD;DAT} \) = time for data signal from SCL LOW to SDA output (HIGH or LOW, depending on which one is worse).

[11] \( t_{VD;ACK} \) = time for Acknowledgement signal from SCL LOW to SDA output (HIGH or LOW, depending on which one is worse).

\[ V_{IL} = 0.3V_{DD} \]
\[ V_{IH} = 0.7V_{DD} \]

Fig 27. Definition of timing for F/S-mode devices on the \( \text{I}^2\text{C} \)-bus
6.2 Hs-mode devices

The I/O levels, I/O current, spike suppression, output slope control and pin capacitance for I^2C-bus Hs-mode devices are given in Table 7. The noise margin for HIGH and LOW levels on the bus lines are the same as specified for F/S-mode I^2C-bus devices.

Figure 28 shows all timing parameters for the Hs-mode timing. The 'normal' START condition S does not exist in Hs-mode. Timing parameters for Address bits, R/W bit, Acknowledge bit and DATA bits are all the same. Only the rising edge of the first SCLH clock signal after an acknowledge bit has a larger value because the external R_p has to pull-up SCLH without the help of the internal current-source.

The Hs-mode timing parameters for the bus lines are specified in Table 8. The minimum HIGH and LOW periods and the maximum rise and fall times of the SCLH clock signal determine the highest bit rate.

With an internally generated SCLH signal with LOW and HIGH level periods of 200 ns and 100 ns respectively, an Hs-mode master fulfills the timing requirements for the external SCLH clock pulses (taking the rise and fall times into account) for the maximum bit rate of 3.4 Mbit/s. So a basic frequency of 10 MHz, or a multiple of 10 MHz, can be used by an Hs-mode master to generate the SCLH signal. There are no limits for maximum HIGH and LOW periods of the SCLH clock, and there is no limit for a lowest bit rate.

Timing parameters are independent for capacitive load up to 100 pF for each bus line allowing the maximum possible bit rate of 3.4 Mbit/s. At a higher capacitive load on the bus lines, the bit rate decreases gradually. The timing parameters for a capacitive bus load of 400 pF are specified in Table 8, allowing a maximum bit rate of 1.7 Mbit/s. For capacitive bus loads between 100 pF and 400 pF, the timing parameters must be interpolated linearly. Rise and fall times are in accordance with the maximum propagation time of the transmission lines SDAH and SCLH to prevent reflections of the open ends.
[1] Devices that use non-standard supply voltages which do not conform to the intended \( \text{I}^2\text{C} \)-bus system levels must relate their input levels to the \( V_{\text{DD}} \) voltage to which the pull-up resistors \( R_p \) are connected.

[2] Devices that offer the level shift function must tolerate a maximum input voltage of 5.5 V at SDA and SCL.

[3] For capacitive bus loads between 100 pF and 400 pF, the rise and fall time values must be linearly interpolated.

[4] SDAH and SCLH I/O stages of Hs-mode slave devices must have floating outputs if their supply voltage has been switched off. Due to the current-source output circuit, which normally has a clipping diode to \( V_{\text{DD}} \), this requirement is not mandatory for the SCLH or the SDAH I/O stage of Hs-mode master devices. This means that the supply voltage of Hs-mode master devices cannot be switched off without affecting the SDAH and SCLH lines.

[5] Special purpose devices such as multiplexers and switches may exceed this capacitance due to the fact that they connect multiple paths together.

### Table 7. Characteristics of the SDAH, SCLH, SDA and SCL I/O stages for Hs-mode \( \text{I}^2\text{C} \)-bus devices

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>HS-mode</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>( V_{\text{IL}} )</td>
<td>LOW-level input voltage</td>
<td>( V_{\text{DD}} &gt; 2 ) V</td>
<td>-0.5</td>
<td>0.3( V_{\text{DD}} ) [1]</td>
</tr>
<tr>
<td>( V_{\text{IH}} )</td>
<td>HIGH-level input voltage</td>
<td>( V_{\text{DD}} &lt; 2 ) V</td>
<td>0</td>
<td>0.4</td>
</tr>
<tr>
<td>( V_{\text{hys}} )</td>
<td>hysteresis of Schmitt trigger inputs</td>
<td>( V_{\text{OL}} ) level, ( I_{\text{OL}} = 3 ) mA</td>
<td>0</td>
<td>0.2( V_{\text{DD}} )</td>
</tr>
<tr>
<td>( R_{\text{onL}} )</td>
<td>transfer gate on resistance for currents between SDA and SDAH, or SCL and SCLH</td>
<td>both signals (SDA and SDAH, or SCL and SCLH) at ( V_{\text{DD}} ) level</td>
<td>50</td>
<td>-</td>
</tr>
<tr>
<td>( R_{\text{onH}} )</td>
<td>transfer gate on resistance between SDA and SDAH, or SCL and SCLH</td>
<td>SCLH output levels between 0.3( V_{\text{DD}} ) and 0.7( V_{\text{DD}} )</td>
<td>3</td>
<td>12</td>
</tr>
<tr>
<td>( I_{\text{CS}} )</td>
<td>pull-up current of the SCLH current-source</td>
<td>output rise time (current-source enabled) with an external pull-up current source of 3 mA</td>
<td>10</td>
<td>40</td>
</tr>
<tr>
<td>( I_{\text{CL}} )</td>
<td>rise time of SCLH signal</td>
<td>capacitive load from 10 pF to 100 pF</td>
<td>10</td>
<td>40</td>
</tr>
<tr>
<td>( I_{\text{CL}} )</td>
<td>rise time of SCLH signal</td>
<td>capacitive load of 400 pF [3]</td>
<td>20</td>
<td>80</td>
</tr>
<tr>
<td>( I_{\text{CL}} )</td>
<td>fall time of SCLH signal</td>
<td>capacitive load from 10 pF to 100 pF</td>
<td>10</td>
<td>40</td>
</tr>
<tr>
<td>( I_{\text{CL}} )</td>
<td>fall time of SCLH signal</td>
<td>capacitive load of 400 pF [3]</td>
<td>20</td>
<td>80</td>
</tr>
<tr>
<td>( I_{\text{SP}} )</td>
<td>pulse width of spikes that must be suppressed by the input filter</td>
<td>SDAH and SCLH</td>
<td>0</td>
<td>10</td>
</tr>
<tr>
<td>( I_{\text{IC}} )</td>
<td>input current each I/O pin</td>
<td>input voltage between 0.1( V_{\text{DD}} ) and 0.9( V_{\text{DD}} )</td>
<td>-</td>
<td>10</td>
</tr>
<tr>
<td>( C_{\text{C}} )</td>
<td>capacitance for each I/O pin [5]</td>
<td>-</td>
<td>10</td>
<td>pF</td>
</tr>
</tbody>
</table>
Table 8. Characteristics of the SDAH, SCLH, SDA and SCL bus lines for Hs-mode \( \text{I}^2\text{C} \)-bus devices\[1\]

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>( C_b = 100 \text{ pF (max)} )</th>
<th>( C_b = 400 \text{ pF[2]} )</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td></td>
<td>Min</td>
<td>Max</td>
<td>Min</td>
</tr>
<tr>
<td>( f_{\text{SCLH}} )</td>
<td>SCLH clock frequency</td>
<td>0</td>
<td>3.4</td>
<td>0</td>
<td>1.7</td>
</tr>
<tr>
<td>( t_{\text{SU;STA}} )</td>
<td>set-up time for a repeated START condition</td>
<td>160</td>
<td>-</td>
<td>160</td>
<td>-</td>
</tr>
<tr>
<td>( t_{\text{HD;STA}} )</td>
<td>hold time (repeated) START condition</td>
<td>160</td>
<td>-</td>
<td>160</td>
<td>-</td>
</tr>
<tr>
<td>( t_{\text{LOW}} )</td>
<td>LOW period of the SCL clock</td>
<td>160</td>
<td>-</td>
<td>320</td>
<td>-</td>
</tr>
<tr>
<td>( t_{\text{HIGH}} )</td>
<td>HIGH period of the SCL clock</td>
<td>60</td>
<td>-</td>
<td>120</td>
<td>-</td>
</tr>
<tr>
<td>( t_{\text{SU;DAT}} )</td>
<td>data set-up time</td>
<td>10</td>
<td>-</td>
<td>10</td>
<td>-</td>
</tr>
<tr>
<td>( t_{\text{HD;DAT}} )</td>
<td>data hold time</td>
<td>0[3]</td>
<td>70</td>
<td>0[3]</td>
<td>150</td>
</tr>
<tr>
<td>( t_{\text{rCL}} )</td>
<td>rise time of SCLH signal</td>
<td>10</td>
<td>40</td>
<td>20</td>
<td>80</td>
</tr>
<tr>
<td>( t_{\text{rCL1}} )</td>
<td>rise time of SCLH signal after a repeated START condition and after an acknowledge bit</td>
<td>10</td>
<td>80</td>
<td>20</td>
<td>160</td>
</tr>
<tr>
<td>( t_{\text{CL}} )</td>
<td>fall time of SCLH signal</td>
<td>10</td>
<td>40</td>
<td>20</td>
<td>80</td>
</tr>
<tr>
<td>( t_{\text{rDA}} )</td>
<td>rise time of SDAH signal</td>
<td>10</td>
<td>80</td>
<td>20</td>
<td>160</td>
</tr>
<tr>
<td>( t_{\text{fDA}} )</td>
<td>fall time of SDAH signal</td>
<td>10</td>
<td>80</td>
<td>20</td>
<td>160</td>
</tr>
<tr>
<td>( t_{\text{SU;STO}} )</td>
<td>set-up time for STOP condition</td>
<td>160</td>
<td>-</td>
<td>160</td>
<td>-</td>
</tr>
<tr>
<td>( C_b )</td>
<td>capacitive load for each bus line</td>
<td>SDAH and SCLH lines</td>
<td>-</td>
<td>100</td>
<td>-</td>
</tr>
<tr>
<td></td>
<td>SDAH + SDA line and SCLH + SCL line</td>
<td>-</td>
<td>400</td>
<td>-</td>
<td>400</td>
</tr>
<tr>
<td>( V_nL )</td>
<td>noise margin at the LOW level</td>
<td>for each connected device (including hysteresis)</td>
<td>0.1V_{DD}</td>
<td>-</td>
<td>0.1V_{DD}</td>
</tr>
<tr>
<td>( V_nH )</td>
<td>noise margin at the HIGH level</td>
<td>for each connected device (including hysteresis)</td>
<td>0.2V_{DD}</td>
<td>-</td>
<td>0.2V_{DD}</td>
</tr>
</tbody>
</table>

[1] All values referred to \( V_{\text{IH(min)}} \) and \( V_{\text{IL(max)}} \) levels (see Table 7).
[2] For bus line loads \( C_b \) between 100 pF and 400 pF the timing parameters must be linearly interpolated.
[3] A device must internally provide a data hold time to bridge the undefined part between \( V_{\text{IH}} \) and \( V_{\eta} \) of the falling edge of the SCLH signal. An input circuit with a threshold as low as possible for the falling edge of the SCLH signal minimizes this hold time.
7. Electrical connections of \(\text{I}^2\text{C}\)-bus devices to the bus lines

### 7.1 Pull-up resistor sizing

The bus capacitance is the total capacitance of wire, connections and pins. This capacitance limits the maximum value of \(R_p\) due to the specified rise time. Figure 29 shows \(R_{p(\text{max})}\) as a function of bus capacitance.

Consider the \(V_{\text{DD}}\) related input threshold of \(V_{\text{IH}} = 0.7V_{\text{DD}}\) and \(V_{\text{IL}} = 0.3V_{\text{DD}}\) for the purposes of RC time constant calculation. Then \(V(t) = V_{\text{DD}} (1 - e^{-t/R_C})\), where \(t\) is the time since the charging started and \(RC\) is the time constant.

\[
V(t1) = 0.3 \times V_{\text{DD}} = V_{\text{DD}} (1 - e^{-t1/RC}); \text{ then } t1 = 0.3566749 \times RC
\]
\[
V(t2) = 0.7 \times V_{\text{DD}} = V_{\text{DD}} (1 - e^{-t2/RC}); \text{ then } t2 = 1.2039729 \times RC
\]

\[
T = t2 - t1 = 0.8473 \times RC
\]

Figure 29 and Equation 1 shows maximum \(R_p\) as a function of bus capacitance for Standard-, Fast- and Fast-mode Plus. For each mode, the \(R_{p(\text{max})}\) is a function of the rise time minimum \(t_r\) from Table 6 and the estimated bus capacitance \(C_b\):

\[
R_{p(\text{max})} = \frac{t_r}{0.8473 \times C_b}
\]

(1)
The supply voltage limits the minimum value of resistor $R_p$ due to the specified minimum sink current of 3 mA for Standard-mode and Fast-mode, or 20 mA for Fast-mode Plus. $R_{p\text{min}}$ as a function of $V_{DD}$ is shown in Figure 30. The traces are calculated using Equation 2:

$$R_{p\text{min}} = \frac{V_{DD} - V_{OL\text{max}}}{I_{OL}}$$

The designer now has the minimum and maximum value of $R_p$ that is required to meet the timing specification. Portable designs with sensitivity to supply current consumption can use a value toward the higher end of the range in order to limit $I_{DD}$.

### 7.2 Operating above the maximum allowable bus capacitance

Bus capacitance limit is specified to limit rise time reductions and allow operating at the rated frequency. While the majority of designs can easily stay within this limit, some applications may exceed it. There are several strategies available to system designers to cope with excess bus capacitance.

- **Reduced $f_{SCL}$ (Section 7.2.1):** The bus may be operated at a lower speed (lower $f_{SCL}$).
- **Higher drive outputs (Section 7.2.2):** Devices with higher drive current such as those rated for Fast-mode Plus can be used (PCA96xx).
- **Bus buffers (Section 7.2.3):** There are a number of bus buffer devices available that can divide the bus into segments so that each segment has a capacitance below the allowable limit, such as the PCA9517 bus buffer or the PCA9546A switch.
- **Switched pull-up circuit (Section 7.2.4):** A switched pull-up circuit can be used to accelerate rising edges by switching a low value pull-up alternately in and out when needed.
7.2.1 Reduced $f_{SCL}$

To determine a lower allowable bus operating frequency, begin by finding the $t_{LOW}$ and $t_{HIGH}$ of the most limiting device on the bus. Refer to individual component data sheets for these values. Actual rise time ($t_r$) will depend on the RC time constant. The most limiting fall time ($t_f$) will depend on the lowest output drive on the bus. Be sure to allow for any devices that have a minimum $t_r$ or $t_f$. Refer to Equation 3 for the resulting $f_{max}$.

$$f_{max} = \frac{I}{t_{LOW(min)} + t_{HIGH(min)} + t_{r(actual)} + t_{f(actual)}}$$  \hspace{1cm} (3)

**Remark:** Very long buses will also have to account for time of flight of signals. Actual results will be slower, as real parts do not tend to control $t_{LOW}$ and $t_{HIGH}$ to the minimum from 30 % to 30 %, or 70 % to 70 %, respectively.

7.2.2 Higher drive outputs

If higher drive devices like the PCA96xx Fast-mode Plus or the P82B bus buffers are used, the higher strength output drivers will sink more current which results in considerably faster edge rates, or, looked at another way, allows a higher bus capacitance. Refer to individual component data sheets for actual output drive capability. Repeat the calculation above using the new values of $C_b$, $R_p$, $t_r$ and $t_f$ to determine maximum frequency. Bear in mind that the maximum rating for $f_{SCL}$ as specified in Table 6 (100 kHz, 400 kHz and 1000 kHz) may become limiting.

7.2.3 Bus buffers, multiplexers and switches

Another approach to coping with excess bus capacitance is to divide the bus into smaller segments using bus buffers, multiplexers or switches. Figure 31 shows an example of a bus that uses a PCA9515 buffer to deal with high bus capacitance. Each segment is then allowed to have the maximum capacitance so the total bus can have twice the maximum capacitance. Keep in mind that adding a buffer always adds delays—a buffer delay plus an additional transition time to each edge, which reduces the maximum operating frequency and may also introduce special $V_{IL}$ and $V_{OL}$ considerations.

Refer to application notes AN255, \textit{I²C / SMBus Repeaters, Hubs and Expanders} and AN262, \textit{PCA954x Family of I²C / SMBus Multiplexers and Switches} for more details on this subject and the devices available from NXP Semiconductors.

---

**Fig 31. Using a buffer to divide bus capacitance**

Note that some buffers allow $V_{DD1}$ and $V_{DD2}$ to be different levels.
7.2.4 Switched pull-up circuit

The supply voltage ($V_{DD}$) and the maximum output LOW level determine the minimum value of pull-up resistor $R_p$ (see Section 7.1). For example, with a supply voltage of $V_{DD} = 5 \, V \pm 10 \%$ and $V_{OL(max)} = 0.4 \, V$ at 3 mA, $R_{p(min)} = (5.5 - 0.4) / 0.003 = 1.7 \, k\Omega$. As shown in Figure 30, this value of $R_p$ limits the maximum bus capacitance to about 200 pF to meet the maximum $t_r$ requirement of 300 ns. If the bus has a higher capacitance than this, a switched pull-up circuit (as shown in Figure 32) can be used.

![Switched pull-up circuit diagram](mbc620)

**Fig 32. Switched pull-up circuit**

The switched pull-up circuit in Figure 32 is for a supply voltage of $V_{DD} = 5 \, V \pm 10 \%$ and a maximum capacitive load of 400 pF. Since it is controlled by the bus levels, it needs no additional switching control signals. During the rising/falling edges, the bilateral switch in the HCT4066 switches pull-up resistor $R_{p2}$ on/off at bus levels between 0.8 V and 2.0 V. Combined resistors $R_{p1}$ and $R_{p2}$ can pull-up the bus line within the maximum specified rise time ($t_r$) of 300 ns.

Series resistors $R_s$ are optional. They protect the I/O stages of the I²C-bus devices from high-voltage spikes on the bus lines, and minimize crosstalk and undershoot of the bus line signals. The maximum value of $R_s$ is determined by the maximum permitted voltage drop across this resistor when the bus line is switched to the LOW level in order to switch off $R_{p2}$.

Additionally, some bus buffers contain integral rise time accelerators. Stand-alone rise time accelerators are also available.
7.3 Series protection resistors

As shown in Figure 33, series resistors ($R_s$) of, e.g., 300 $\Omega$ can be used for protection against high-voltage spikes on the SDA and SCL lines (resulting from the flash-over of a TV picture tube, for example). If series resistors are used, designers must add the additional resistance into their calculations for $R_p$ and allowable bus capacitance.

![Figure 33. Series resistors ($R_s$) for protection against high-voltage spikes](image)

The required noise margin of 0.1$V_{DD}$ for the LOW level, limits the maximum value of $R_s$. $R_{s\text{max}}$ as a function of $R_p$ is shown in Figure 34. Note that series resistors will affect the output fall time.

![Figure 34. Maximum value of $R_s$ as a function of the value of $R_p$ with supply voltage as a parameter](image)
7.4 Input leakage

The maximum HIGH level input current of each input/output connection has a specified maximum value of 10 µA. Due to the required noise margin of 0.2V<sub>DD</sub> for the HIGH level, this input current limits the maximum value of R<sub>p</sub>. This limit depends on V<sub>DD</sub>. The total HIGH-level input current is shown as a function of R<sub>p(max)</sub> in Figure 35.

![Figure 35. Total HIGH-level input current as a function of the maximum value of R<sub>p</sub> with supply voltage as a parameter](image)

7.5 Wiring pattern of the bus lines

In general, the wiring must be so chosen that crosstalk and interference to/from the bus lines is minimized. The bus lines are most susceptible to crosstalk and interference at the HIGH level because of the relatively high impedance of the pull-up devices.

If the length of the bus lines on a PCB or ribbon cable exceeds 10 cm and includes the V<sub>DD</sub> and V<sub>SS</sub> lines, the wiring pattern should be:

SDA _______________________
V<sub>DD</sub> _______________________
V<sub>SS</sub> _______________________
SCL _______________________

If only the V<sub>SS</sub> line is included, the wiring pattern should be:

SDA _______________________
V<sub>SS</sub> _______________________
SCL _______________________

These wiring patterns also result in identical capacitive loads for the SDA and SCL lines. The V<sub>SS</sub> and V<sub>DD</sub> lines can be omitted if a PCB with a V<sub>SS</sub> and/or V<sub>DD</sub> layer is used.
If the bus lines are twisted-pairs, each bus line must be twisted with a V_{SS} return. Alternatively, the SCL line can be twisted with a V_{SS} return, and the SDA line twisted with a V_{DD} return. In the latter case, capacitors must be used to decouple the V_{DD} line to the V_{SS} line at both ends of the twisted pairs.

If the bus lines are shielded (shield connected to V_{SS}), interference will be minimized. However, the shielded cable must have low capacitive coupling between the SDA and SCL lines to minimize crosstalk.

### 8. Abbreviations

<table>
<thead>
<tr>
<th>Acronym</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>A/D</td>
<td>Analog-to-Digital</td>
</tr>
<tr>
<td>ATCA</td>
<td>Advanced Telecom Computing Architecture</td>
</tr>
<tr>
<td>BMC</td>
<td>Baseboard Management Controller</td>
</tr>
<tr>
<td>CMOS</td>
<td>Complementary Metal Oxide Semiconductor</td>
</tr>
<tr>
<td>cPCI</td>
<td>compact Peripheral Component Interconnect</td>
</tr>
<tr>
<td>D/A</td>
<td>Digital-to-Analog</td>
</tr>
<tr>
<td>DIP</td>
<td>Dual In-line Package</td>
</tr>
<tr>
<td>EEPROM</td>
<td>Electrically Erasable Programmable Read Only Memory</td>
</tr>
<tr>
<td>HW</td>
<td>Hardware</td>
</tr>
<tr>
<td>I/O</td>
<td>Input/Output</td>
</tr>
<tr>
<td>I^{2}C-bus</td>
<td>Inter-Integrated Circuit bus</td>
</tr>
<tr>
<td>IC</td>
<td>Integrated Circuit</td>
</tr>
<tr>
<td>IPMI</td>
<td>Intelligent Platform Management Interface</td>
</tr>
<tr>
<td>LCD</td>
<td>Liquid Crystal Display</td>
</tr>
<tr>
<td>LED</td>
<td>Light Emitting Diode</td>
</tr>
<tr>
<td>LSB</td>
<td>Least Significant Bit</td>
</tr>
<tr>
<td>MCU</td>
<td>Microcontroller</td>
</tr>
<tr>
<td>MSB</td>
<td>Most Significant Bit</td>
</tr>
<tr>
<td>NMOS</td>
<td>Negative-channel Metal Oxide Semiconductor</td>
</tr>
<tr>
<td>PCB</td>
<td>Printed-Circuit Board</td>
</tr>
<tr>
<td>PCI</td>
<td>Peripheral Component Interconnect</td>
</tr>
<tr>
<td>PMBus</td>
<td>Power Management Bus</td>
</tr>
<tr>
<td>RAM</td>
<td>Random Access Memory</td>
</tr>
<tr>
<td>ROM</td>
<td>Read-Only Memory</td>
</tr>
<tr>
<td>SMBus</td>
<td>System Management Bus</td>
</tr>
<tr>
<td>SPI</td>
<td>Serial Peripheral Interface</td>
</tr>
<tr>
<td>UART</td>
<td>Universal Asynchronous Receiver/Transmitter</td>
</tr>
<tr>
<td>USB</td>
<td>Universal Serial Bus</td>
</tr>
</tbody>
</table>
9. Legal information

9.1 Definitions

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